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To the Honorable Commissioner of Patents

original document(s) or copy thereof.

1. Name of conveying party(ies) (assignor(s)):

Robert J. FALSTER

Additional name(s) of conveying party(ies) attached?  yes  no

2. Name and address of Party(ies) receiving an interest (assignee(s)):

Name: MI MC Electronic Materials, Inc

Address: 50 Pearl Drive

P. O. Box 8

City: St. Peters

State: Missouri / Zip: 63376

Country: U.S.A

Additional name(s) & address(es) attached?  yes  no

3. Nature of Conveyance:

- Assignment
- Merger
- Change of Name
- Certified Translation
- Security Agreement
- Other \_\_\_\_\_

Execution Date: October 29, 1999

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date(s) of the application is: \_\_\_\_\_

A. Patent Application No(s):

09387288

B. Patent No(s):

Others on additional sheet(s) attached?  Yes  No

5. Name and address of party to whom correspondence concerning document should be mailed:

Edward J. Hejlek  
 Senniger, Powers, Leavitt & Roedel  
 One Metropolitan Square  
 16th Floor  
 St. Louis, Missouri 63102  
 (314) 231-5400 (telephone)

6. Total number of applications and patents involved:

Application(s) 1 + Patent(s):     = Total 1

7. Total Fee (37 CFR 3.41) ..... \$ 40.00

- Enclosed
- Authorized to be charged to deposit account

8. Deposit Account Number: **19-1345**

(Duplicate copy of this sheet attached)

- Charge any underpayment or credit any overpayment to above Deposit Account

DO NOT USE THIS SPACE

9. Statement and signature

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Edward J. Hejlek

Name of Person Signing

Signature

11/18/99

Date

Total number of pages including cover sheet, attachments, and document:

12/14/1999 TTON11 00000153 09387288

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ASSIGNMENT

**WHEREAS, I**, Robert J. Falster of Milano, Italy have invented an improvement in SILICON ON INSULATOR STRUCTURE FROM LOW DEFECT DENSITY SINGLE CRYSTAL SILICON (file MEMC 98-3050 (2512)) and have executed an application for a United States patent based thereon Serial No. 09/387,288, filed August 31, 1999;

**AND, WHEREAS**, MEMC Electronic Materials, Inc. of St. Peters, Missouri, a corporation of the State of Delaware (hereinafter referred to as "ASSIGNEE"), is desirous of acquiring certain rights thereunder;

**NOW, THEREFORE**, for one dollar and other good and valuable consideration, receipt of all of which is hereby acknowledged, I have agreed to and do hereby sell, assign, and transfer unto said ASSIGNEE the entire right, title, and interest in and throughout the United States of America (including its territories and dependencies) and all countries foreign thereto in and to said invention, said United States application, any other United States applications (including provisional, non-provisional, divisional, continuing, or reissue applications) based in whole or in part on said United States application or in whole or in part on said invention, any foreign applications based in whole or in part on any of the aforesaid United States applications or in whole or in part on said invention, and any and all patents (including extensions thereof) of any country which have been or may be granted on any of the aforesaid applications or on said invention or any part thereof;

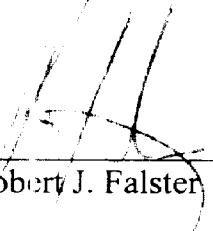
**TO BE HELD AND ENJOYED** by said ASSIGNEE, its successors and assigns, as fully and entirely as the same would have been held and enjoyed by me had no sale and assignment of said interest been made;


AND I hereby authorize and request the Commissioner of Patents of the United States of America to issue any and all United States patents which may be granted upon said United States applications or any of them, or upon said invention or any part thereof, to said ASSIGNEE;

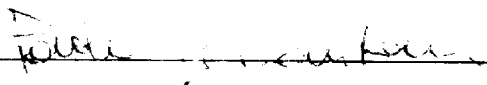
AND I hereby agree for myself and for my heirs, executors and administrators, to execute without further consideration any further lawful documents and any further assurances, and any provisional, non-provisional, divisional, continuing, reissue, or other applications for patents of any country, that may be deemed necessary by said ASSIGNEE fully to secure to said ASSIGNEE its interest as aforesaid in and to said invention or any part thereof, and in and to said several patents or any of them;

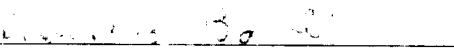
AND I hereby covenant for myself and my legal representatives, and agree with said ASSIGNEE, its successors and assigns, that I have granted no right or license to make, use or sell said invention, to anyone except said ASSIGNEE, that prior to the execution of this deed my right, title, and interest in said invention had not been otherwise encumbered, and that I have not executed and will not execute any instrument in conflict herewith.

IN WITNESS WHEREOF, I have hereunto set my hand.

  
\_\_\_\_\_  
Robert J. Falster

  
\_\_\_\_\_  
Date

Witness:   
\_\_\_\_\_

Witness:   
\_\_\_\_\_